



Microelectronic Packaging & Assembly Solutions

Press Release

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QUIK-PAK AWARDED PLAQUE BY IMAPS

San Diego, CA, September 27, 2011, - Quik-Pak, a division of Delphon Industries and leader in Microelectronic Packaging and Assembly, was awarded a plaque today by the International Microelectronics and Packaging Society (IMAPS) for their support as a premier corporate member of the organization.

The International Microelectronics and Packaging Society is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. IMAPS produces numerous publications, workshops, international conferences, professional development courses, and exhibitions *bringing together the entire microelectronics supply chain.*

.About Quik-Pak:

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The company specializes in microelectronic packaging and advanced assembly services. A limitless array of open-cavity and open molded packages are available with no minimum quantity. Packaging can be provided as part of a turnkey assembly solution along with backgrinding, wafer dicing, die/wire bonding, laser micromachining, remolding and marking/branding. Custom assembly services are also offered for flip chip, ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced costs for new devices, while providing excellent flexibility, quality and customer service.

For further information:

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